Low-Voltage CMOS Quad 2-Input Multiplexer

With 5 V-Tolerant Inputs (Inverting)

The MC74LCX158 is a high performance, quad 2–input inverting multiplexer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX158 inputs to be safely driven from 5 V devices.

Four bits of data from two sources can be selected using the Select and Enable inputs. The four outputs present the selected data in the inverted form. The MC74LCX158 can also be used as a function generator. Current drive capability is 24 mA at the outputs.

Features

- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
 - ♦ Human Body Model >2000 V
 - ♦ Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

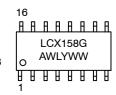


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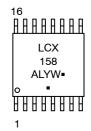
http://onsemi.com











A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

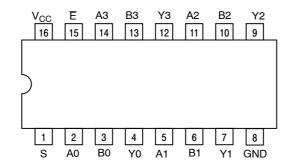


Figure 1. Pinout: 16-Lead Plastic Package (Top View)

PIN NAMES

Pins	Function
An	Source 0 Data Inputs
Bn	Source 1 Data Inputs
Ē	Enable Input
S	Select Input
Yn	Outputs

TRUTH TABLE

Inp	uts	Outputs
Output Enable	Select	Y0-Y3
Н	Х	Н
L	L	A0-A3
L	Н	B0-B3

X = Don't Care
A0-A3, B0-B3 = The levels of the respective
Data-Word Inputs

PIN DESCRIPTIONS

INPUTS

A0-A3 (Pins 2, 5, 11, 14)

Nibble A inputs. The data present on these pins is transferred to the outputs when the Select input is at a low level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

B0-B3 (Pins 3, 6, 10, 13)

Nibble B inputs. The data present on these pins is transferred to the outputs when the Select input is at a high level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

OUTPUTS

Y0-Y3 (Pins 4, 7, 9, 12)

Data outputs. The selected input nibble is presented at these outputs when the Output Enable input is at a low level. The data present on these pins is in its inverted form for the LCX158. For the Output Enable input at a high level, the outputs are at a high level for the LCX158.

Select (Pin 1)

Nibble select. This input determines the data word to be transferred to the outputs. A low level on this input selects the A inputs and a high level selects the B inputs.

CONTROL INPUTS

Enable (Pin 15)

Output Enable input. A low level on this input allows the selected data to be presented at the outputs. A high level on this input sets all of the outputs to a high level for the LCX158.

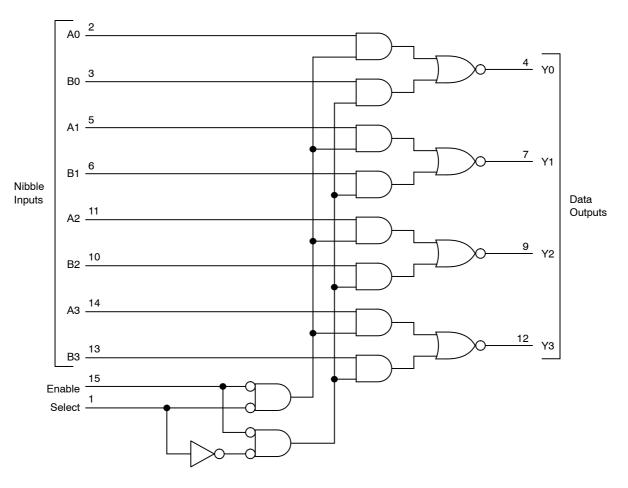


Figure 2. Expanded Logic Diagram

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX158DG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74LCX158DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX158DTG	TSSOP-16 (Pb-Free)	96 Units / Rail
MC74LCX158DTR2G	TSSOP-16 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_{\parallel} \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	Vo > Vcc	mA
Ιο	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.3 to 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
V _O	Output Voltage (HIGH or LOW State) (3-State)	0		V _{CC}	V
I _{OH}	$\begin{array}{l} \text{HIGH Level Output Current} \\ \text{$V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$} \\ \text{$V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$} \\ \text{$V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$} \end{array}$			-24 -12 -8	mA
l _{OL}	LOW Level Output Voltage V _{CC} = 3.0 V - 3.6 V V _{CC} = 2.7 V - 3.0 V V _{CC} = 2.3 V - 2.7 V			+24 +12 +8	mA
T _A	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°C	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Units
V _{IH}	Minimum HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		V
		$2.7 \text{ V} \le \text{V}_{CC} \le 3.0 \text{ V}$	2.0		
		$3.0 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$	2.0		
V _{IL}	Maximum LOW Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	V
		$2.7 \text{ V} \le \text{V}_{CC} \le 3.0 \text{ V}$		0.8	
		$3.0 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$		8.0	
V _{OH}	Minimum HIGH Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = -100 \mu\text{A}$	V _{CC} - 0.2		V
		$V_{CC} = 2.3 \text{ V; } I_{OH} = -8 \text{ mA}$	1.7		
		$V_{CC} = 2.7 \text{ V}; I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	Maximum LOW Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = 100 \mu\text{A}$		0.2	V
		$V_{CC} = 2.3 \text{ V}; I_{OH} = 8 \text{ mA}$		0.7	
		$V_{CC} = 2.7 \text{ V}; I_{OH} = 12 \text{ mA}$		0.4	
		V _{CC} = 3.0 V; I _{OH} = 16 mA		0.4	
		$V_{CC} = 3.0 \text{ V; } I_{OH} = 24 \text{ mA}$		0.55	
I _{OFF}	Power Off Leakage Current	V _{CC} = 0, V _{IN} = 5.5 V or V _{OUT} = 5.5 V		10	μΑ
I _{IN}	Input Leakage Current	V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND		±5	μΑ
I _{CC}	Quiescent Supply Current	V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND		10	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

^{2.} These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS

		Limits						
				$T_A = -40^{\circ}C$	C to +85°C			
		V _{CC} = 3.0	V ± 3.6 V	V _{CC} =	2.7 V	V _{CC} = 2.3	V to 2.7 V	
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
t _{PLH}	Propagation Delay	1.0	6.5	1.0	7.5	1.0	8.5	ns
t_{PHL}	A or B to Y	1.0	6.5	1.0	7.5	1.0	8.5	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t_{PHL}	S to Y	1.0	7.0	1.0	8.0	1.0	9.0	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t_{PHL}	Output Enable to Y	1.0	7.0	1.0	8.0	1.0	9.0	
toshl	Output-to-Output Skew		1.0					ns
toslh			1.0					

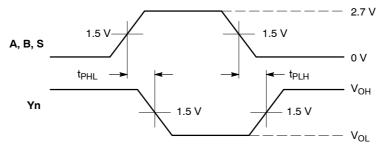
DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V _{OLP}	Dynamic LOW Peak Voltage (Note 3)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 3)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V

^{3.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

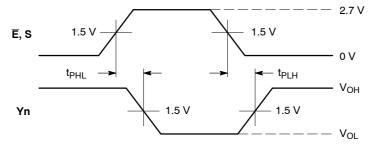
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	25	pF



WAVEFORM 1 - INVERTING PROPAGATION DELAYS

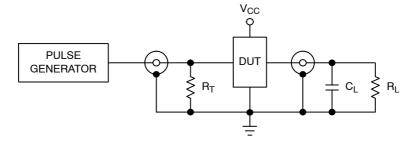
 t_R = t_F = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns



WAVEFORM 2 - INVERTING PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 3. AC Waveforms



 C_L = 50 pF or equivalent (Includes jig and probe capacitance)

 $R_L = R_1 = 500 \Omega$ or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

MECHANICAL CASE OUTLINE



DATE 29 DEC 2006

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- THE NOTION AND TOLETANOING FER ANSI'Y 14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- PHOI HUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR PROTRUSION

 SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D

 DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
C	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
7	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

16. COLLECTOR 16. CATHODE 16. COLLECTOR, #4 16. EMITTER, #1 STYLE 5: STYLE 6: STYLE 7: PIN 1. DRAIN, DYE #1 PIN 1. CATHODE 2. COMMON DRAIN (OUTPUT) 3. DRAIN, #1 2. CATHODE 2. COMMON DRAIN (OUTPUT) 4. DRAIN, #2 3. CATHODE 3. COMMON DRAIN (OUTPUT) 5. DRAIN, #3 5. CATHODE 4. GATE P-CH 7. DRAIN, #3 6. CATHODE 5. COMMON DRAIN (OUTPUT) 8. DRAIN, #4 7. CATHODE 7. COMMON DRAIN (OUTPUT) 8. DRAIN, #4 8. CATHODE 8. SOURCE P-CH 9. GATE, #4 9. ANODE 9. SOURCE P-CH 10. SOURCE, #4 10. ANODE 10. COMMON DRAIN (OUTPUT) 11. GATE, #3 11. ANODE 11. COMMON DRAIN (OUTPUT) 12. SOURCE, #3 12. ANODE 13. GATE N-CH 14. SOURCE, #2 14. ANODE 14. COMMON DRAIN (OUTPUT) 15. GATE, #1 15. ANODE 16. SOURCE N-CH 16. SOURCE, #1 16. ANODE 16. SOURCE N-CH	STYLE 1: PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13. 14.	COLLECTOR BASE EMITTER NO CONNECTION EMITTER BASE	2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12.	CATHODE CATHODE ANODE NO CONNECTION CATHODE CATHODE NO CONNECTION	STYLE 3: PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13. 14.	COLLECTOR, DYE #1 BASE, #1 EMITTER, #1 COLLECTOR, #1 COLLECTOR, #2 BASE, #2 EMITTER, #2 COLLECTOR, #2 COLLECTOR, #3 BASE, #3 EMITTER, #3 COLLECTOR, #3 COLLECTOR, #4	STYLE 4: PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13.	COLLECTOR, DYE #1 COLLECTOR, #1 COLLECTOR, #2 COLLECTOR, #3 COLLECTOR, #3 COLLECTOR, #4 COLLECTOR, #4 EMITTER, #4 BASE, #4 EMITTER, #4 BASE, #3 EMITTER, #3 BASE, #2 EMITTER, #2 BASE, #1		FOOTPRINT
STYLE 5:										
	PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13.	DRAIN, #1 DRAIN, #2 DRAIN, #2 DRAIN, #3 DRAIN, #3 DRAIN, #3 DRAIN, #4 DRAIN, #4 GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3 GATE, #2 SOURCE, #2 GATE, #1	PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13.	CATHODE CATHODE CATHODE CATHODE CATHODE CATHODE CATHODE CATHODE CATHODE ANODE	PIN 1. 2. 3. 4. 5. 6. 7. 8. 9. 10. 11. 12. 13.	COMMON DRAIN (OUTPUT COMMON DRAIN (OUTPUT GATE P-CH COMMON DRAIN (OUTPUT COMMON DRAIN (OUTPUT COMMON DRAIN (OUTPUT SOURCE P-CH SOURCE P-CH COMMON DRAIN (OUTPUT COMMON DRAIN (OUTPUT COMMON DRAIN (OUTPUT GATE N-CH COMMON DRAIN (OUTPUT GATE N-CH COMMON DRAIN (OUTPUT COMMON DRAIN COMMON DRAIN (OUTPUT COMMON DRAIN COMMON DRAIN COMMON DRAIN (OUTPUT COMMON DRAIN COMMON DRAIN COMMON DRAIN COMMON DRAIN COMMON DRAI	n n n n n n	16X 0.58	<u> </u>	16X 1.12

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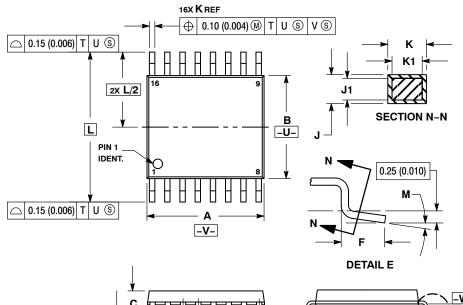
-T- SEATING PLANE





TSSOP-16 CASE 948F-01 ISSUE B

DATE 19 OCT 2006



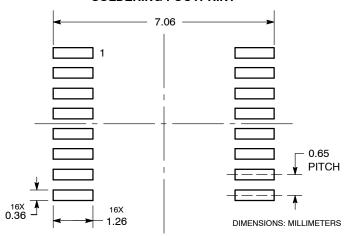
NOTES

- JIES:
 DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD
 FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD EL ROLL OF GATE BURDS SUAL NO.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.18	0.28	0.007	0.011
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
Ы	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT

G



GENERIC MARKING DIAGRAM*

168888888 XXXX XXXX **ALYW** 188888888

XXXX = Specific Device Code Α = Assembly Location

= Wafer Lot L Υ = Year W = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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